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2812

AMENDMENT TRANSMITTAL LETTERDocket No.
M4065.0239/P239Application No.
09/653,561-Conf. #5354Filing Date
August 31, 2000Examiner
H. N. NguyenArt Unit
2812

Applicant(s): Larry Hillyer et al.

Invention: METHOD AND MATERIAL FOR REMOVING ETCH RESIDUE FROM HIGH ASPECT RATIO CONTACT SURFACES

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	122	- 133 =		x	0.00
Independent Claims	13	- 15 =		x	0.00
Multiple Dependent Claims (check if applicable)					<input type="checkbox"/>
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00

 Large Entity Small Entity No additional fee is required for this amendment. Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed. A check in the amount of \$ _____ to cover the filing fee is enclosed. Payment by credit card. Form PTO-2038 is attached. The Director is hereby authorized to charge and credit Deposit Account No. 04-1073
as described below. A duplicate copy of this sheet is enclosed. Credit any overpayment. Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.
Thomas J. D'Amico
Attorney Reg. No.: 28,371

Dated: April 14, 2004

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Docket No.: M4065.0239/P239
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Larry Hillyer et al.

Confirmation No.: 5354

Application No.: 09/653,561

Art Unit: 2812

Filed: August 31, 2000

Examiner: H. N. Nguyen

For: METHOD AND MATERIAL FOR
REMOVING ETCH RESIDUE FROM
HIGH ASPECT RATIO CONTACT
SURFACES

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated January 14, 2004 (Paper No. 18), please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 15 of this paper.